

Title (en)
Printed circuit board mounting facility

Title (de)
Einrichtung zur Montage einer Leiterplatte

Title (fr)
Dispositif pour monter une plaquette de circuit imprimé

Publication
EP 1237400 A3 20040421 (EN)

Application
EP 02251469 A 20020301

Priority
US 79847601 A 20010302

Abstract (en)
[origin: EP1237400A2] A facility for mounting an electronic component includes a first circuit board having mounting apertures. A mounting element is associated with each aperture, and includes a boss defining a bore. The boss has a first surface contacting a major surface of the first circuit board, and a second surface opposite the first surface. A pin is received in the bore, and has a lower portion protruding from the first surface of the boss and into one of the apertures. The pin's lower portion defines a space to capture a portion of the first circuit board. A fastener connected to the pin may generate compression between the space and the boss to secure the board, and a corner-shaped protrusion on the second surface may constrain the corner periphery of a second board resting on the second surface, with the fastener also securing the second board against the boss.
<IMAGE>

IPC 1-7
H05K 7/14; **F16B 5/06**

IPC 8 full level
H05K 1/18 (2006.01); **H05K 1/14** (2006.01); **H05K 7/14** (2006.01)

CPC (source: EP KR US)
H05K 1/14 (2013.01 - KR); **H05K 7/142** (2013.01 - EP US); **Y10T 24/30** (2015.01 - EP US); **Y10T 24/42** (2015.01 - EP US); **Y10T 24/44752** (2015.01 - EP US)

Citation (search report)
• [X] DE 3427680 A1 19860206 - SIEMENS AG [DE]
• [X] US 5460543 A 19951024 - KOSMALA MICHAEL L [US]
• [X] DE 9419847 U1 19950202 - FORSCH PROF DR ING HABIL DR PH [DE]

Cited by
EP1978602A3; EP1602117B2

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
EP 1237400 A2 20020904; **EP 1237400 A3 20040421**; JP 2002324961 A 20021108; JP 4156849 B2 20080924; KR 100869269 B1 20081118; KR 20020070840 A 20020911; TW 535472 B 20030601; US 2002121008 A1 20020905; US 6543098 B2 20030408

DOCDB simple family (application)
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